



CALICE DAQ Developments

DAQ overview DIF functionality and implementation EUDET Prototype development path

Imperial College London



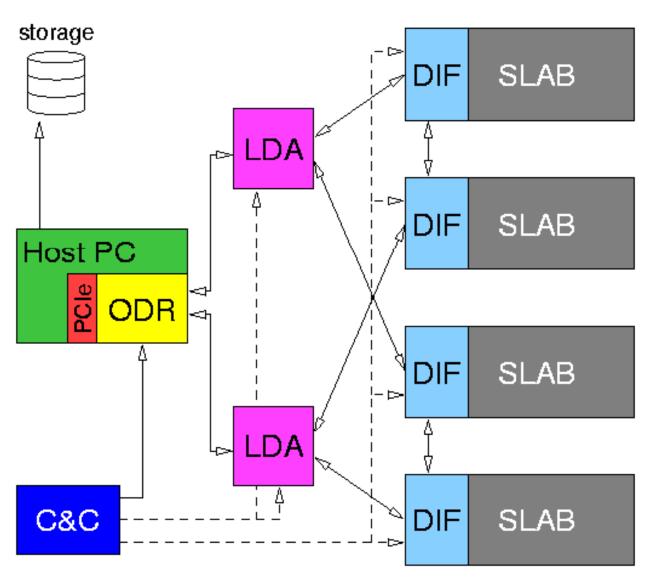






DAQ architecture





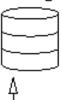
- Slab hosts VFE chips
- DIF connected to Slab
- LDA servicing DIFs
- LDAs read out by ODR
- PC hosts ODR, through PClexpress
- C&C routes clock, controls

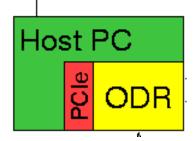










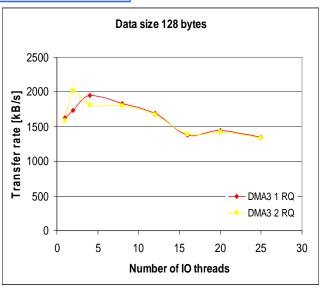


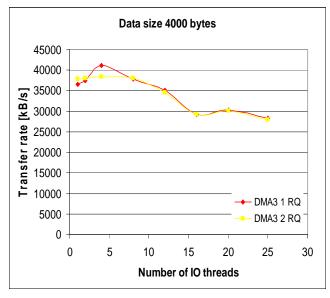


 ODR is a commercial FPGA board with PCIe interface

(Virtex4-FX100, PCIe 8x, etc.)

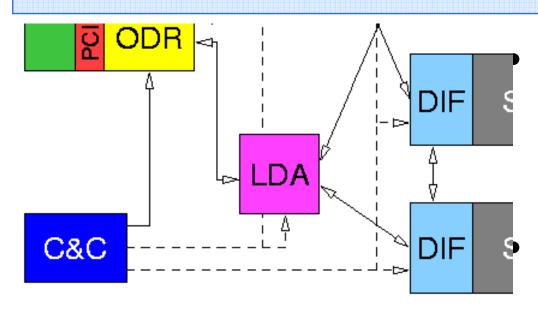
- Custom firm- and software
- DMA driver pulls data off the onboard RAM, writes to disk
- Performance studies& optimisation





Clock & Controls Distribution





C&C unit provides machine clock and fast signals to ODR, LDA (and DIF?)

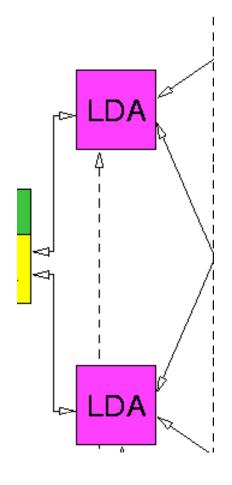
Clock jitter requirement seems not outrageous (at the moment)

- Fast Controls: encoded through the LDA-DIF link
- Low-latency fast signals: distributed 'directly'

LDA and link to ODR





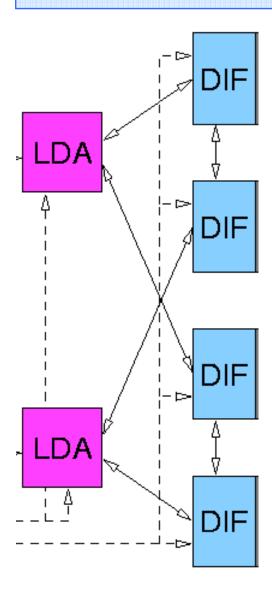




- Enterpoint Xilinx Spartan3 based dev. board
- RAM & lots of I/O (including PCI)
- 1st Prototype is again a commercial FPGA board with custom firmware and hardware add-ons:
 - Gbit ethernet and Glink Rx/Tx for ODR link -probably optical
 - Many links towards DIFs

LDA-DIF link





LDA-DIF link:

- Serial link running at multiple of machine clock
- 50Mbps (raw) bandwidth minimum
- robust encoding (8B/10B or alike)
- anticipating 8...16 DIFs on an LDA, bandwidth permitting
- LDAs serve even/odd DIFs for redundancy





	Gnd	2	3	Clk+	Pair1 (STP)
Pair2 (STP)	DL2D+	4	5	Clk- Gnd	
	Gnd	8	7	DD2L+	Pair3 (STP)
Pair4 (STP)	SpD2L+	10	11	DD2L- Gnd	
	SpD2L- Pow2	12 14	13	Pow1	
	SpL2D-	16	15 17	SpL2D+ Gnd	Pair5 (UTP)
	Pow3	18	19	Pow4	
Possible Pinout for HDMI					
(Based on SAMTEC HPDPI					
cable signal designation)					

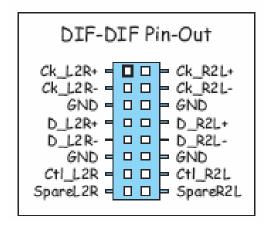
clock
data
control
spare data
spare control

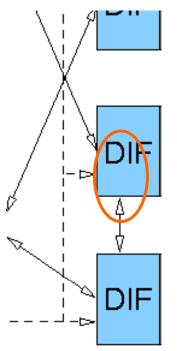
LDA-DIF link physical form factor:

- Differential signals on shielded twisted pairs
- Few single-ended control lines
- HDMI connectors and cabling: high quality, commercially available

DIF-DIF link



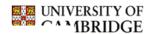


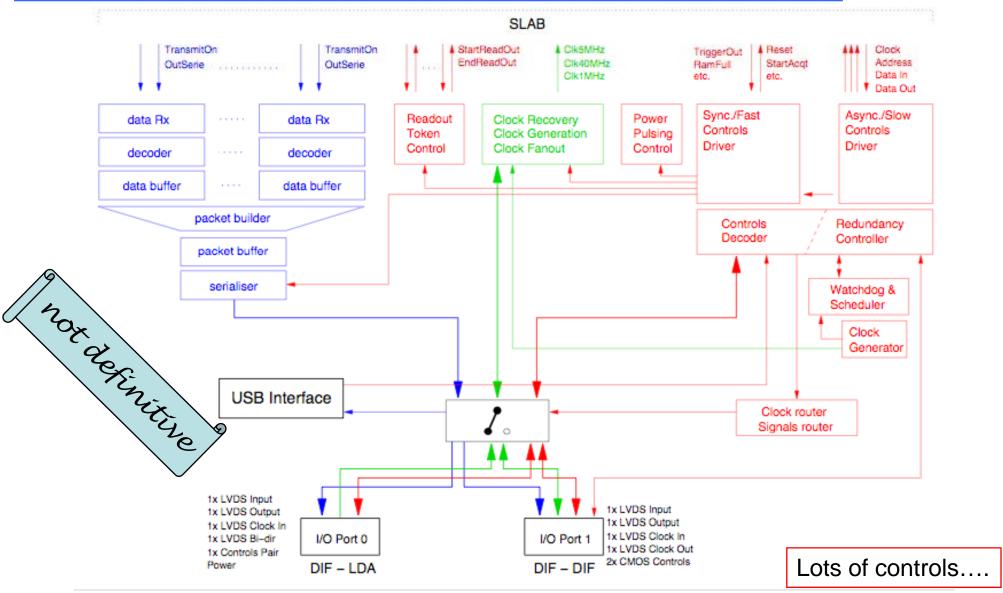


- Redundancy against loss of LDA link
- Provides differential signals:
 - Clock in both directions
 - Data and Control connections
 - Two spares: one each direction
- Plus two single-ended control lines
- Single LDA-DIF link bandwidth sufficiently large for data of two DIFs



Draft DIF block diagram





DIF Functionality



- Receive, regenerate and distribute clocks
- Receive, buffer, package and send data from VFE to LDA
- Receive and decode incoming commands and issue corresponding signals
- Control the DIF-DIF redundancy connection
- Receive, decode and distribute slow control commands
- Control power pulsing and provide watchdog functionality
- Provide an USB interface for stand-alone running and debugging
-on top of that: all the things we did not think of so far

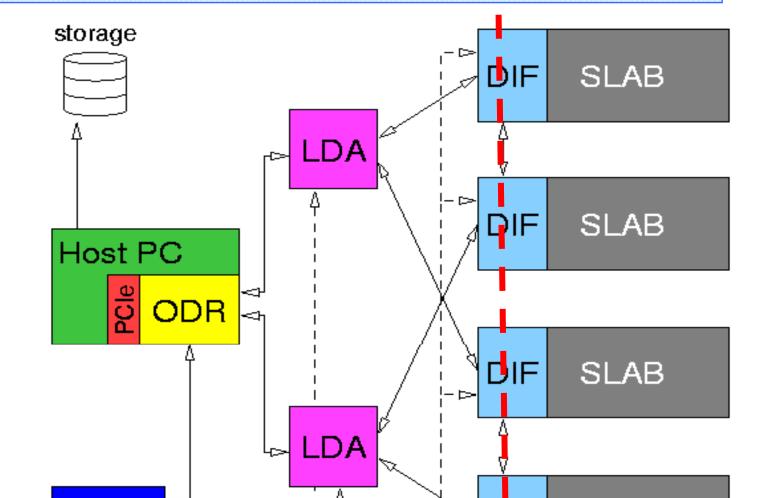
DIF implementation



- The Slab is an integral part of the detector
- The LDA and ODR are transparent wrt detector type
- The DIF and its interface to the slab is detector-specific
- Large parts of the DIF firmware can/should/must be generalised
- DIF hardware should support firmware to profit from common developments
- DIF working group to address common problems and share knowledge, experience, and VHDL code

Opportunity to memorise the acronyms:





SLAB

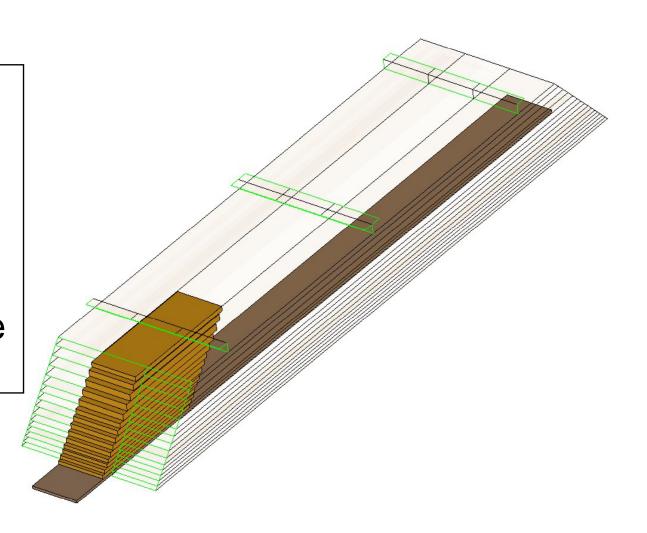
C&C

The EUDET prototype



UNIVERSITY OF CAMBRIDGE

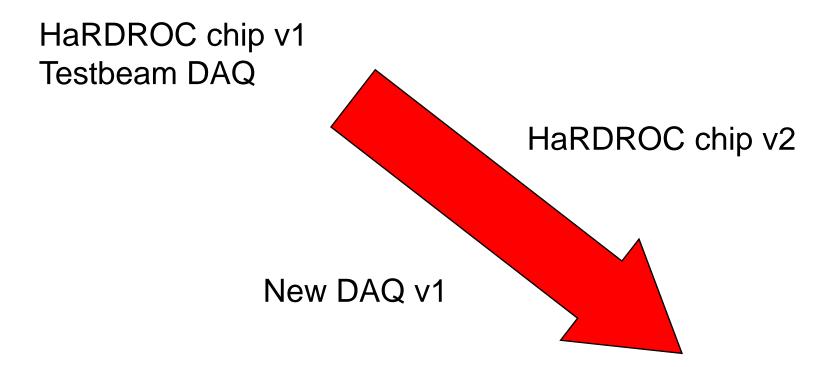
- Full stack: 15 slabs, instrumented on both sides
- As close to CALICE technology as reasonably possible



Prototype development



NOW 2008 2009



EUDET proto: detector + DAQ

Technology prototype for physics results



EUDET module is quite a large and complex object. Keep future production in mind:

- large objects are assemblies of smaller objects
- develop testable objects

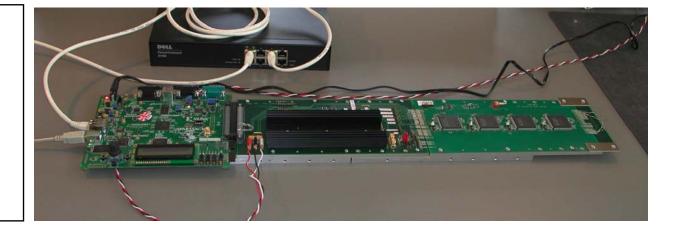
Many technology options require even more R&D:

- power consumption
- data rate: speed vs. power
- noise
- etc.

R&D for the EUDET prototype



- Proto-slab:
 - FPGA for VFEs
 - provisional 'DIF'for ECAL



- Tests of signal distribution along long PCB lines: signal deterioration, termination options, speed, etc.
- Identification of possible issues with many (pseudo)VFE chips on long transmission paths
- Familiarise with VFE readout architecture





Much more to come.....